

What is claimed is:

1. A process for forming a ridgy resin film,
comprising the steps of:

forming a first concave and a second concave on a
5 surface of a plate substrate to make an area between said
first and second concaves as a resin film formation area;

supplying a resin liquid containing a
photopolymerizable resin onto a surface of said resin film
formation area to form a resin liquid layer of said resin
10 liquid; and

curing said resin liquid layer to form a ridgy resin
film.

2. The process for forming a ridgy resin film
according to claim 1, said resin liquid layer is cured by
15 irradiation with ultraviolet rays.

3. The process for forming a ridgy resin film
according to claim 1, wherein during the step of forming
said first concave and said second concave, a boundary
between said resin film formation area and said first
20 concave and that between said resin film formation area and
said second concave are raised to form ridges, and said
ridgy resin film is formed between said ridges.

4. The process for forming a ridgy resin film
according to claim 1, wherein said first and second
25 concaves are formed by scraping a surface of said substrate

by pressing an excavator against the surface of said substrate.

5 5. The process for forming a ridgy resin film according to claim 1, said first and second concaves are formed by irradiating a surface of said substrate with a laser beam.

6. The process for forming a ridgy resin film according to claim 1, wherein said first and second concaves are formed in concentric relation.

10 7. The process for forming a ridgy resin film according to claim 1, wherein a viscosity of said resin liquid at 25°C is not lower than 10 mPa·s nor higher than 1,000 mPa·s.

15 8. The process for forming a ridgy resin film according to claim 7, wherein the viscosity of said resin liquid at 25°C exceeds 100 mPa·s.

20 9. The process for forming a ridgy resin film according to claim 7, wherein a glass transition temperature of a resin forming said ridgy resin film is not lower than 60°C and below 100°C.

10. The process for forming a ridgy resin film according to claim 8, wherein the glass transition temperature of a resin forming said ridgy resin film is not lower than 60°C and below 100°C.

25 11. The process for forming a ridgy resin film

according to claim 1, wherein a height from the surface of
said resin film formation area to a surface of said ridgy
resin film is 3 μ m or higher.

12. A process for producing a recording medium molded
in a form of a disk and having a recording layer and a
resin layer provided on said recording layer, said process
comprising the steps of;

forming ring-shaped first and second concaves on a
surface of said resin layer with a center of said recording
medium as centers to form an area between said first and
second concaves as a resin film formation area;

supplying a resin liquid containing a
photopolymerizable resin onto said resin film formation;
and

curing said resin liquid layer to give a ridgy resin
film.

13. A recording medium molded in a form of a disk and
having a recording layer and a resin layer provided on said
recording layer, wherein ring-shaped first and second
concaves with a center of said recording medium as centers,
a resin film formation area between said first and second
concaves, and a ridgy resin film formed in said resin film
formation area are formed on a surface of said resin layer,
and said ridgy resin film is raised above a surface of said
resin layer.

Amended
14. The recording medium according to claim 13,
wherein said resin layer is made of a polycarbonate resin.

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